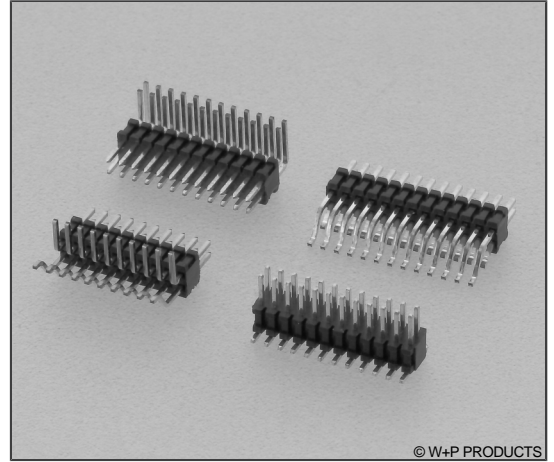


## SMT-/ Mixed Technology Stiftleisten RM 1,27mm, 2-reihig SMT/Mixed Technology Pin Headers, 1.27mm Pitch, Double Row

### Technische Daten / Technical Data

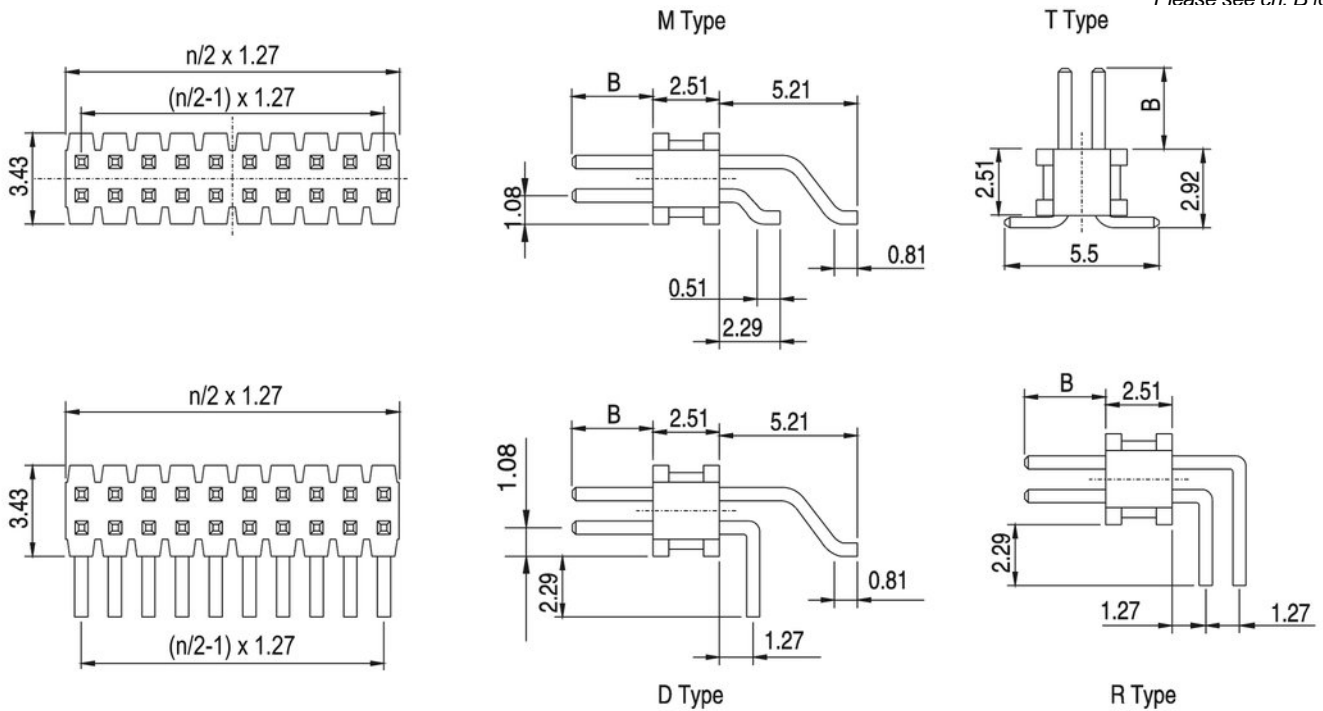
Isolierkörper	Thermoplast, nach UL94 V-0
Insulator	Thermoplastic, rated UL94 V-0
Kontaktmaterial	Vierkantstift 0,40mm, Kupferlegierung
Contact Material	0.40mm square pin, copper alloy
Kontaktoberfläche	Lt. Oberflächenoptionen, über Ni (1,3 ... 2,5µm)
Contact Surface	Acc. to options (see below), over Ni (1.3 ... 2.5µm)
Durchgangswiderstand	< 20 mΩ
Contact Resistance	< 20 mΩ
Isolationswiderstand	> 500 MΩ
Insulation Resistance	> 500 MΩ
Spannungsfestigkeit	500 V AC
Test Voltage	500 V AC
Nennspannung	250 V AC
Voltage Rating	250 V AC
Nennstrom	1 A
Current Rating	1 A
Temperaturbereich	-40 °C ... +105 °C
Temperature Range	-40 °C ... +105 °C
Verarbeitung	Reflow- oder Wellen-Lötverfahren
Processing	Reflow- or wave soldering



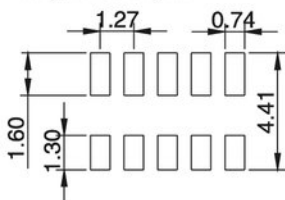
© W+P PRODUCTS

Passende Buchsenleisten:  
Compatible Female Headers:  
**713 7130** etc.

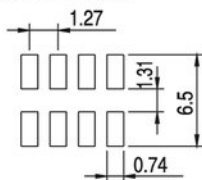
Weitere siehe Kapitel B  
Please see ch. B for more



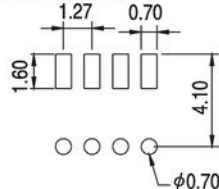
M Type P.C.B Layout



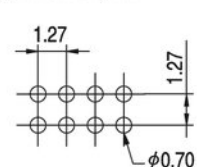
T Type P.C.B Layout



D Type P.C.B Layout



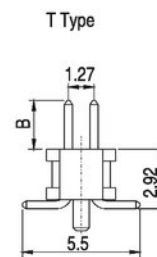
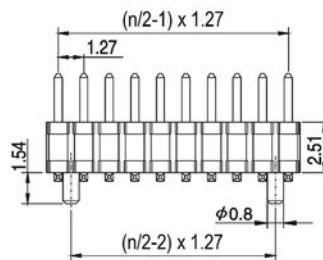
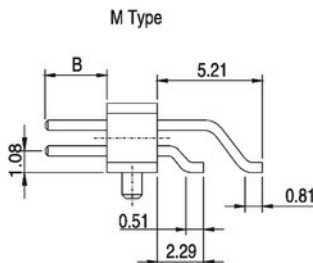
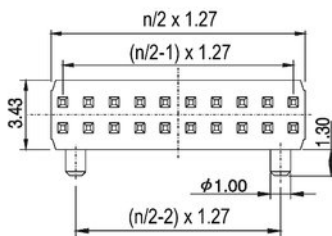
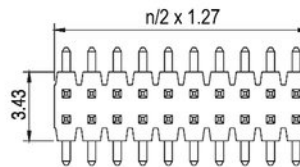
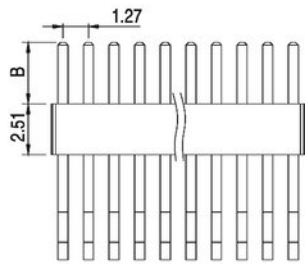
R Type P.C.B Layout



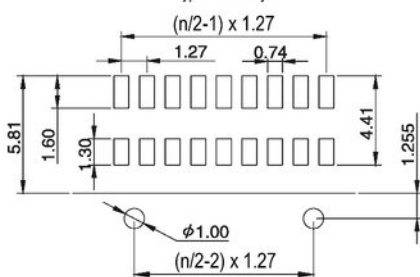
Series	Type*	Dimensions*	Contacts*	Plating*	Loc. Pegs	Packaging*
<b>7076</b>	<b>1</b>	<b>10</b>	<b>004</b>	<b>50</b>	<b>00</b>	<b>PPST</b>
	1 D-Type 2 M-Type 3 T-Type 4 R-Type	10 B=3,05mm 20 B=1,91mm 30 B=1,65mm 40 B=3,81mm	004-100 Zweireihig Double row	00 Vergoldet Gold plated 50 Verzinkt Tin plated 60 Sel. Au/Sn Duplex plating	00 Ohne Pos.hilfen W/o loc. pegs	ST PPST PPTR (Option)

# 7076

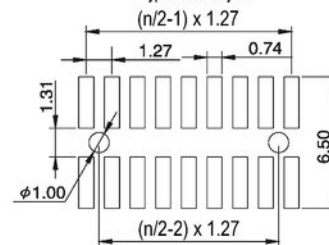
SMT-/ Mixed Technology Stifflisten RM 1,27mm, 2-reihig  
SMT/Mixed Technology Pin Headers, 1.27mm Pitch, Double Row



M Type P.C.B Layout



T Type P.C.B Layout



Series	Type*	Dimensions*	Contacts*	Plating*	Loc. Pegs	Packing*
<b>7076</b>	<b>2</b>	<b>10</b>	<b>004</b>	<b>50</b>	<b>10</b>	<b>PPST</b>
	2 M-Type 3 T-Type	10 B=3,05mm 20 B=1,91mm 30 B=1,65mm 40 B=3,81mm	004-100 Zweireihig Double row	00 Vergoldet Gold plated 50 Verzinkt Tin plated 60 Sel. Au/Sn Duplex plating	10 Mit Pos.hilfen With loc.pegs	ST In Stangen ohne Pick&Place-Pads In tubes w/o Pick&Place-Pads PPST In Stangen mit P&P-Pads In tubes with P&P-Pads PPTR (Option) Tape & Reel mit P&P-Pads Tape & Reel with P&P-Pads

\* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.  
\* This is an **order example** - please replace by your specifications.

#### Lieferformen / Packaging Options:

ST In Stangen ohne Pick&Place-Pads / In tubes w/o Pick&Place-Pads  
PPST In Stangen mit P&P-Pads / In tubes with P&P-Pads  
PPTR (Option) Tape & Reel mit P&P-Pads / Tape & Reel with P&P-Pads

### Reflow-Lötempfehlung

*Reflow Soldering Recommendation*

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Lötten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_{Smin}$	150 °C
Temperatur Maximum $T_{Smax}$	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich $T_L$	217 °C
Verweildauer oberhalb $T_L$	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur $T_P$	260±5 °C
Dauer Höchsttemperatur	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur $T_P$	max. 8m

*Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).*

Profile Feature	Key Values
Minimum Temperature $T_{Smin}$	150 °C
Maximum Temperatur $T_{Smax}$	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature $T_L$	217 °C
Duration above $T_L$	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature $T_P$	260±5 °C
Duration Peak Temperature	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. $T_P$	max. 8min

